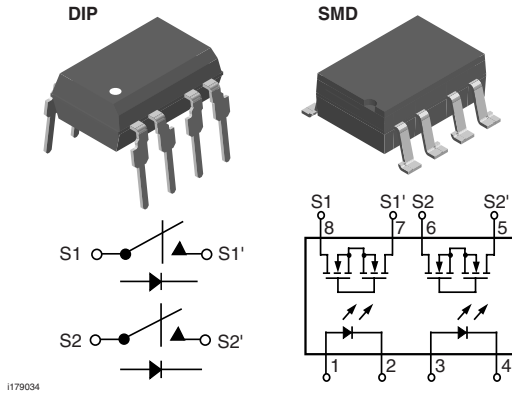


Dual 1 Form A Solid State Relay



FEATURES

- Dual channel (LH1500)
- Current limit protection
- Isolation test voltage 5300 V_{RMS}
- Typical R_{ON} 20 Ω
- Load voltage 350 V
- Load current 150 mA
- High surge capability
- Clean bounce free switching
- Low power consumption
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS
COMPLIANT

DESCRIPTION

The LH1520 dual 1 form A relays are SPST normally open switches that can replace electromechanical relays in many applications. They are constructed using a GaAlAs LED for actuation control and an integrated monolithic die for the switch output. The die, fabricated in a high-voltage dielectrically isolated technology is comprised of a photodiode array, switch control circuitry, and MOSFET switches. In addition, the LH1520 SSRs employ current limiting circuitry, enabling them to pass FCC 68.302 and other regulatory surge requirements when overvoltage protection is provided.

APPLICATIONS

- General telecom switching
 - On/off hook control
 - Ring delay
 - Dial pulse
 - Ground start
 - Ground fault protection
- Instrumentation
- Industrial controls

AGENCY APPROVALS

- UL1577: file no. E52744 system code H or J, double protection
- CSA: certification no. 093751
- BSI/BABT: certification no. 7980
- DIN EN: 60747-5-2 (VDE 0884)/60747-5-5 pending
- FIMKO: approval

ORDER INFORMATION

PART	REMARKS	PACKAGE
LH1520AAC	Tubes	SMD-8
LH1520AACTR	Tape and reel	SMD-8
LH1520AB	Tubes	DIP-8

ABSOLUTE MAXIMUM RATINGS (1)

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
SSR				
LED continuous forward current		I _F	50	mA
LED reverse voltage	I _R ≤ 10 μA	V _R	8.0	V
DC or peak AC load voltage	I _L ≤ 50 μA	V _L	350	V
Continuous DC load current, one pole operating		I _L	150	mA

LH1520AB/LH1520AAC/LH1520AACTR



Vishay Semiconductors Dual 1 Form A Solid State Relay

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
SSR				
Continuous DC load current, two poles operating		I_L	110	mA
Peak load current (single shot), form B	$t = 100 \text{ ms}$	I_P	⁽³⁾	
Ambient temperature range		T_{amb}	- 40 to + 85	°C
Storage temperature range		T_{stg}	- 40 to + 150	°C
Pin soldering temperature ⁽⁴⁾	$t = 10 \text{ s max.}$	T_{sld}	260	°C
Input to output isolation test voltage	$t = 1.0 \text{ s}, I_{ISO} = 10 \text{ } \mu\text{A max.}$	V_{ISO}	5300	V_{RMS}
Pole-to-pole isolation voltage (S1 to S2) ⁽²⁾ (dry air, dust free, at sea level)			1600	V
Output power dissipation (continuous)		P_{diss}	600	mW

Notes

⁽¹⁾ $T_{amb} = 25 \text{ } ^\circ\text{C}$, unless otherwise specified.

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.

⁽²⁾ Breakdown occurs between the output pins external to the package.

⁽³⁾ Refer to current limit performance application note for a discussion on relay operation during transient currents.

⁽⁴⁾ Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP).

ELECTRICAL CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
INPUT						
LED forward current, switch turn-on	$I_L = 100 \text{ mA}, t = 10 \text{ ms}$	I_{Fon}		1.0	2.0	mA
LED forward current, switch turn-off	$V_L = \pm 300 \text{ V}$	I_{Foff}	0.2	1.1		mA
LED forward voltage	$I_F = 10 \text{ mA}$	V_F	1.15	1.26	1.45	V
OUTPUT						
On-resistance	$I_F = 5.0 \text{ mA}, I_L = 50 \text{ mA}$	R_{ON}	12	20	25	Ω
Off-resistance	$I_F = 0 \text{ mA}, V_L = \pm 100 \text{ V}$	R_{OFF}	0.5	300		$G\Omega$
Current limit	$I_F = 5.0 \text{ mA}, t = 5.0 \text{ ms}, V_L = \pm 6.0 \text{ V}$	I_{LMT}	230	270	370	mA
Off-state leakage current	$I_F = 0 \text{ mA}, V_L = \pm 100 \text{ V}$	I_O		0.32	200	nA
	$I_F = 0 \text{ mA}, V_L = \pm 350 \text{ V}$	I_O			1.0	μA
Output capacitance	$I_F = 0 \text{ mA}, V_L = 1.0 \text{ V}$	C_O		55		pF
	$I_F = 0 \text{ mA}, V_L = 50 \text{ V}$	C_O		10		pF
Pole-to-pole capacitance (S1 to S2)	$I_F = 5.0 \text{ mA}$			0.5		pF
Switch offset	$I_F = 5.0 \text{ mA}$	V_{OS}		0.15		μV
TRANSFER						
Capacitance (input to output)	$V_{ISO} = 1.0 \text{ V}$	C_{IO}		1.1		pF
Turn-on time	$I_F = 5.0 \text{ mA}, I_L = 50 \text{ mA}$	t_{on}		1.4	2.0	ms
Turn-off time	$I_F = 5.0 \text{ mA}, I_L = 50 \text{ mA}$	t_{off}		0.7	2.0	ms

Note

$T_{amb} = 25 \text{ } ^\circ\text{C}$, unless otherwise specified.

Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements.

TYPICAL CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

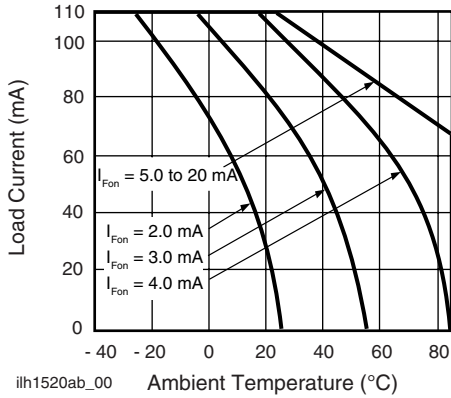


Fig. 1 - Recommended Operating Conditions

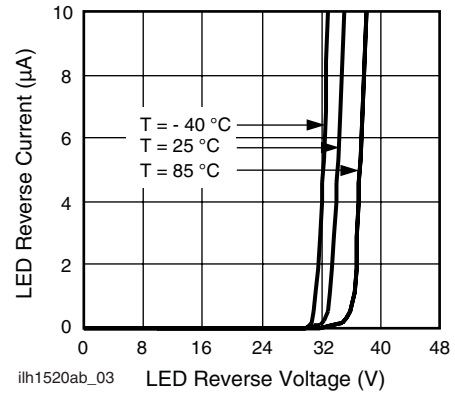


Fig. 4 - LED Reverse Current vs. LED Reverse Voltage

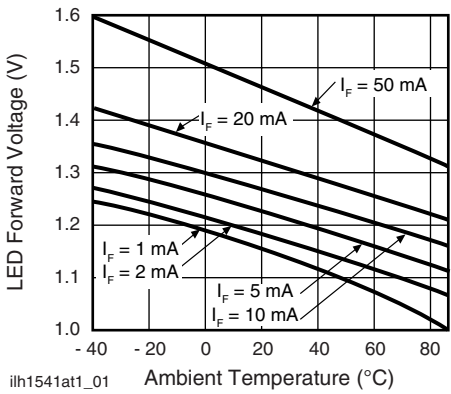


Fig. 2 - LED Voltage vs. Temperature

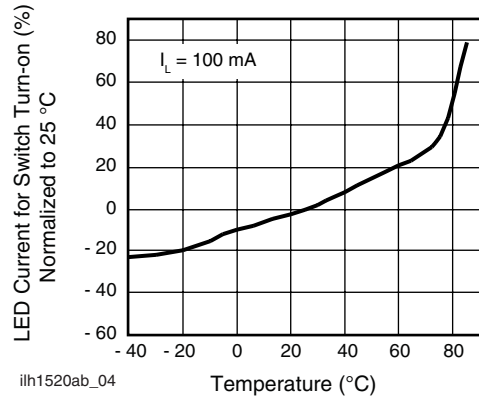


Fig. 5 - LED Current for Switch Turn-on vs. Temperature

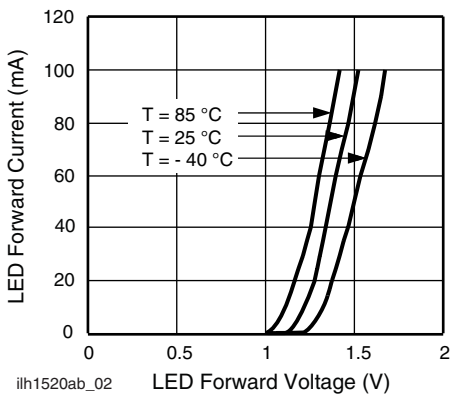


Fig. 3 - LED Forward Current vs. LED Forward Voltage

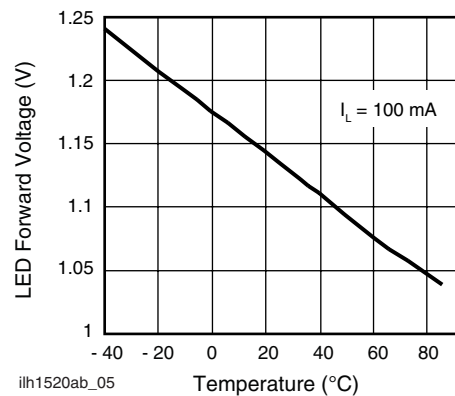


Fig. 6 - LED Dropout Voltage vs. Temperature

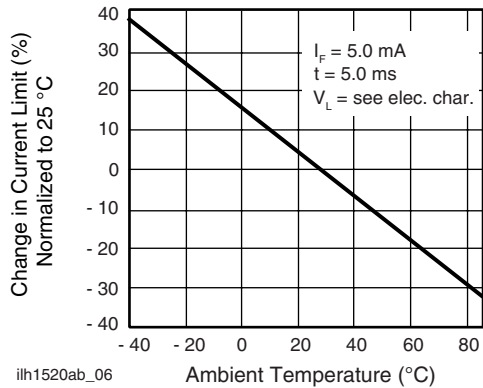


Fig. 7 - Current Limit vs. Temperature

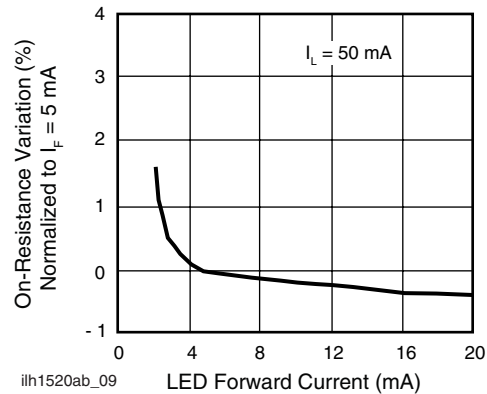


Fig. 10 - Variation in On-Resistance vs. LED Current

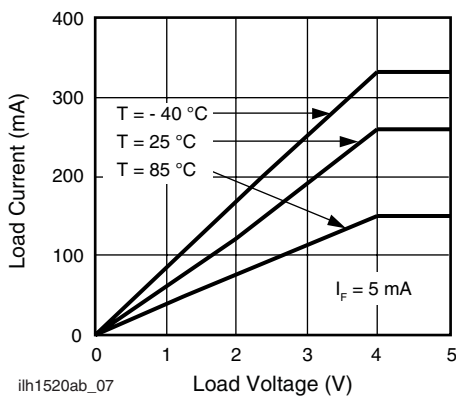


Fig. 8 - Load Current vs. Load Voltage

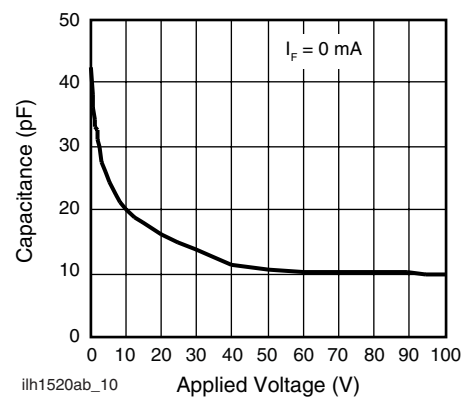


Fig. 11 - Switch Capacitance vs. Applied Voltage

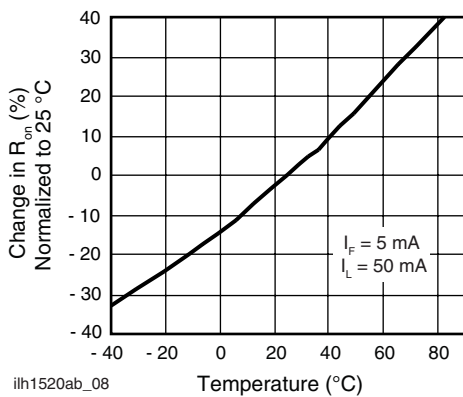


Fig. 9 - On-Resistance vs. Temperature

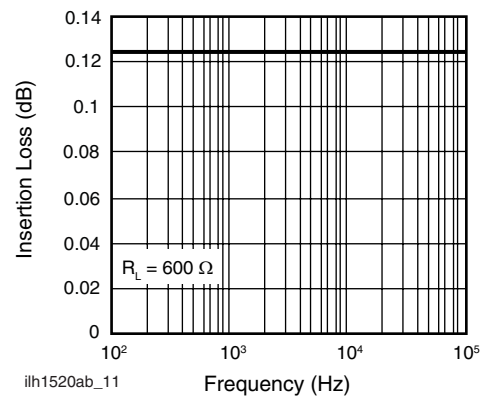
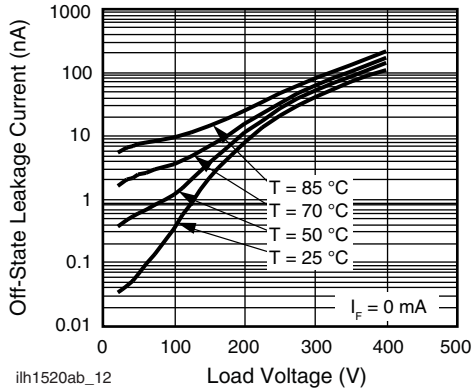


Fig. 12 - Insertion Loss vs. Frequency



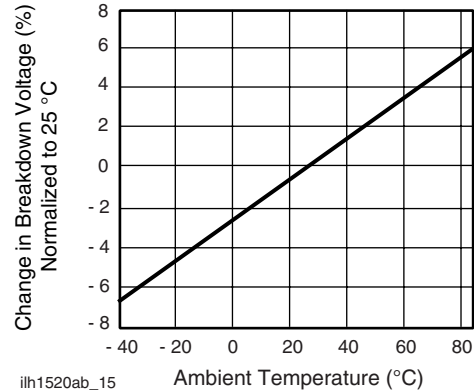
LH1520AB/LH1520AAC/LH1520ACTR

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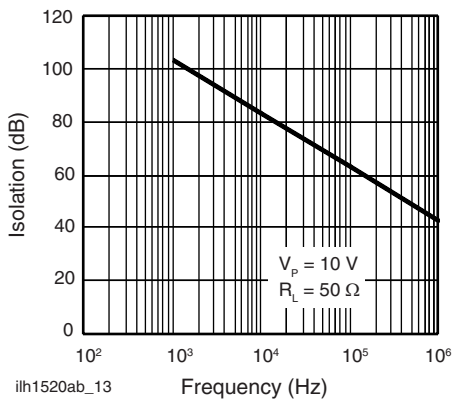
ilh1520ab_12

Fig. 13 - Leakage Current vs. Applied Voltage



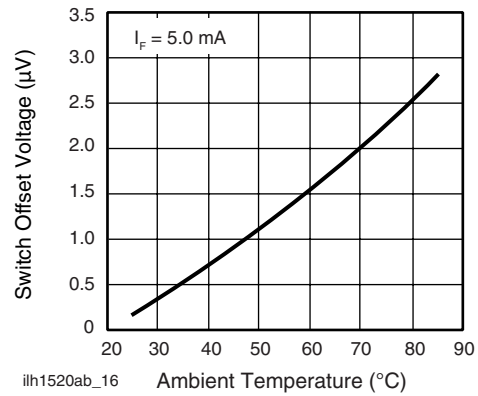
ilh1520ab_15

Fig. 16 - Switch Breakdown Voltage vs. Temperature



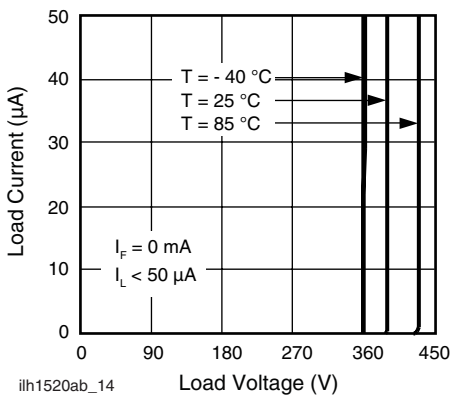
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Fig. 14 - Output Isolation



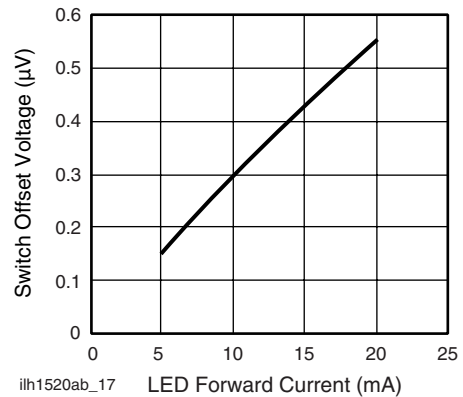
ilh1520ab_16

Fig. 17 - Switch Offset Voltage vs. Temperature



ilh1520ab_14

Fig. 15 - Switch Breakdown Voltage vs. Load Current



ilh1520ab_17

Fig. 18 - Switch Offset Voltage vs. LED Current

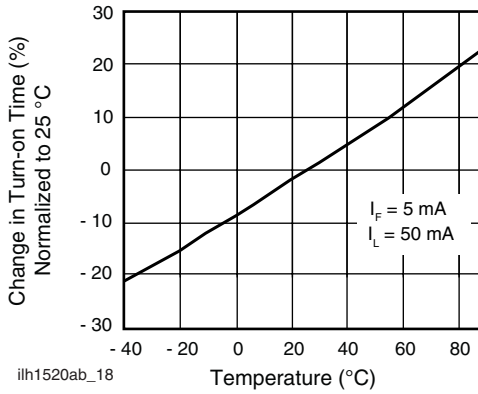


Fig. 19 - Turn-on Time vs. Temperature

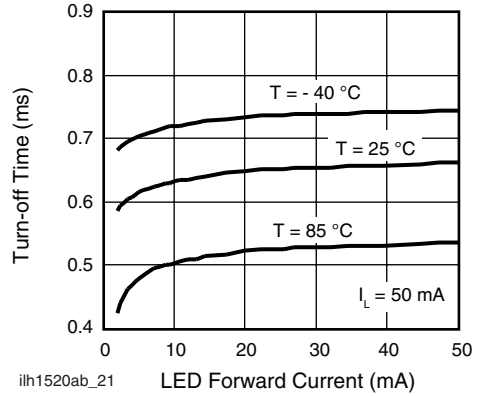


Fig. 22 - Turn-off Time vs. LED Current

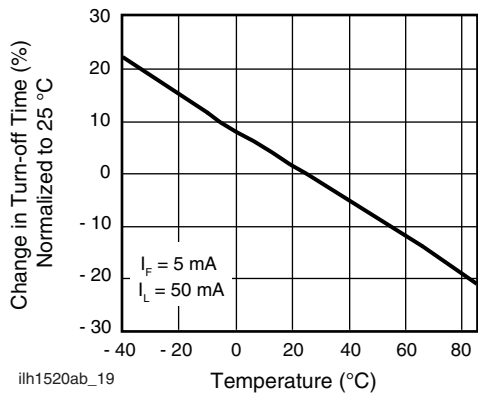


Fig. 20 - Turn-off Time vs. Temperature

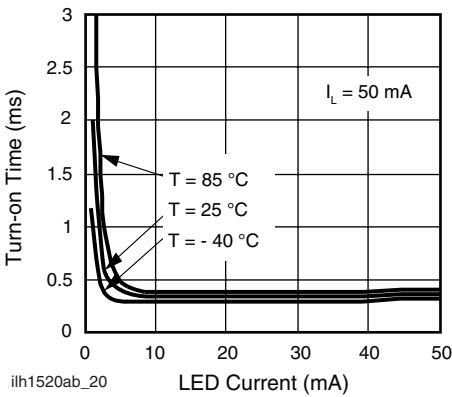


Fig. 21 - Turn-on Time vs. LED Current

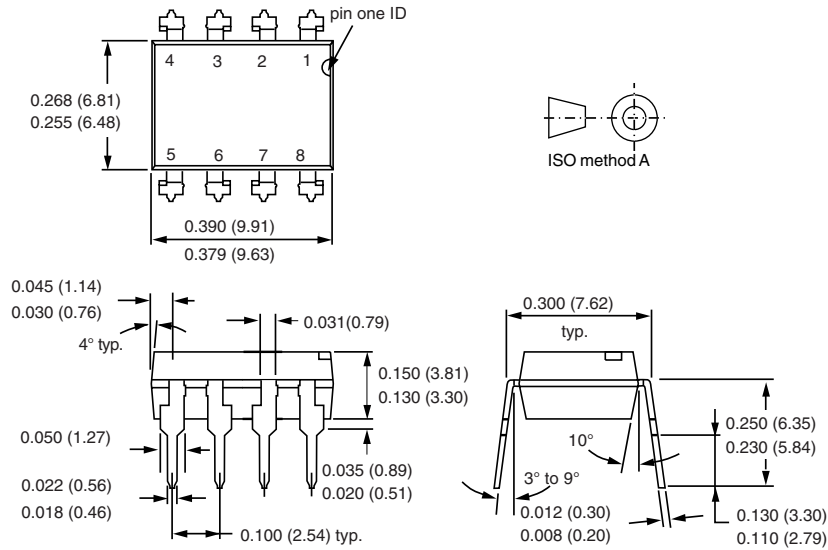


LH1520AB/LH1520AAC/LH1520AACTR

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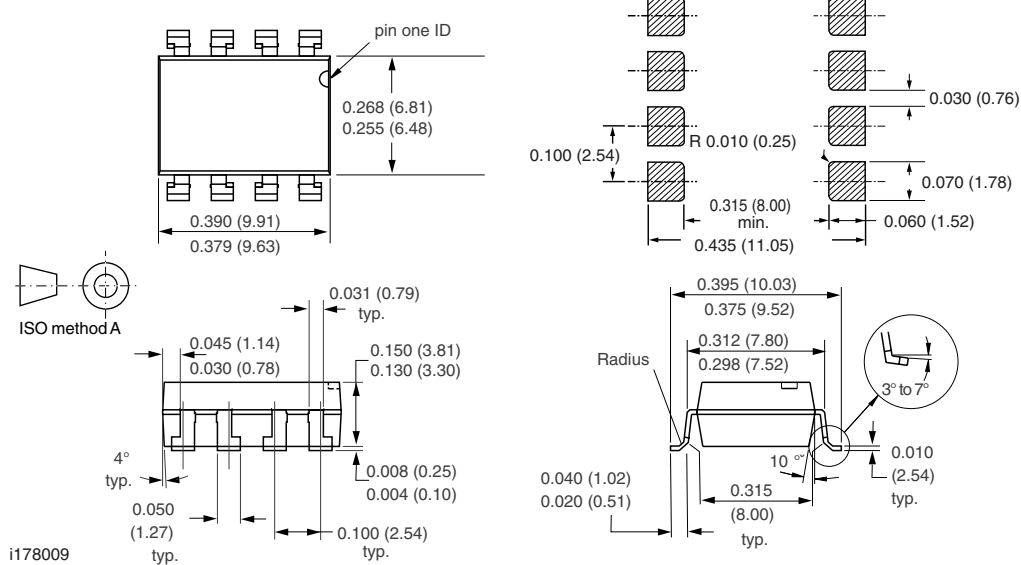
PACKAGE DIMENSIONS in inches (millimeters)

DIP



i178008

SMD



i178009



OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively.
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA.
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design
and may do so without further notice.

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Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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